

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

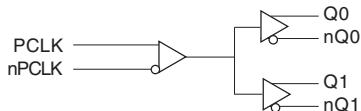
GENERAL DESCRIPTION

 The ICS853011C is a low skew, high performance 1-to-2 Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS853011C is characterized to operate from either a 2.5V or a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS853011C ideal for those clock distribution applications demanding well defined performance and repeatability.

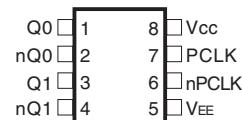
FEATURES

- 2 differential 2.5V/3.3V LVPECL / ECL outputs
- 1 differential PCLK, nPCLK input pair
- PCLK, nPCLK pair can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Output frequency: 3GHz
- Translates any single ended input signal to 3.3V LVPECL levels with resistor bias on nPCLK input
- Output skew: 5ps (typical)
- Part-to-part skew: TBD
- Propagation delay: 250ps (typical)
- LVPECL mode operating voltage supply range: $V_{CC} = 2.375V$ to $3.8V$, $V_{EE} = 0V$
- ECL mode operating voltage supply range: $V_{CC} = 0V$, $V_{EE} = -3.8V$ to $-2.375V$
- $-40^{\circ}C$ to $85^{\circ}C$ ambient operating temperature
- Pin compatible with MC100LVEP11 and SY100EP11U

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS853011C
8-Lead SOIC

3.90mm x 4.90mm x 1.37mm package body
M Package
Top View

ICS853011C

8-Lead TSSOP, 118 mil

3mm x 3mm x 0.95mm package body
G Package
Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

TABLE 1. PIN DESCRIPTIONS

| Number | Name | Type | Description | | |
|--------|----------|--------|--|---|--|
| 1, 2 | Q0, nQ0 | Output | Differential output pair. LVPECL interface levels. | | |
| 3, 4 | Q1, nQ1 | Output | Differential output pair. LVPECL interface levels. | | |
| 5 | V_{EE} | Power | Negative supply pin. | | |
| 6 | nPCLK | Input | Pullup/ Pulldown | Clock input. LVPECL interface levels. | |
| 7 | PCLK | Input | Pulldown | Clock input. Default LOW when left floating. LVPECL interface levels. | |
| 8 | V_{CC} | Power | | Positive supply pin. | |

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

| Symbol | Parameter | Test Conditions | Minimum | Typical | Maximum | Units |
|----------------|-------------------------|-----------------|---------|---------|---------|-----------|
| $R_{PULLDOWN}$ | Input Pulldown Resistor | | | 75 | | $K\Omega$ |
| R_{PULLUP} | Input Pullup Resistor | | | 37 | | $K\Omega$ |



Integrated
Circuit
Systems, Inc.

PRELIMINARY

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

ABSOLUTE MAXIMUM RATINGS

| | |
|--|-----------------------------------|
| Supply Voltage, V_{CC} | 4.6V (LVPECL mode, $V_{EE} = 0$) |
| Negative Supply Voltage, V_{EE} | -4.6V (ECL mode, $V_{CC} = 0$) |
| Inputs, V_I (LVPECL mode) | -0.5V to $V_{CC} + 0.5V$ |
| Inputs, V_I (ECL mode) | 0.5V to $V_{EE} - 0.5V$ |
| Outputs, I_O | |
| Continuous Current | 50mA |
| Surge Current | 100mA |
| Operating Temperature Range, TA | -40°C to +85°C |
| Storage Temperature, T_{STG} | -65°C to 150°C |
| Package Thermal Impedance, θ_{JA} (Junction-to-Ambient) for 8 Lead SOIC | 112.7°C/W (0 lfpm) |
| Package Thermal Impedance, θ_{JA} (Junction-to-Ambient) for 8 Lead TSSOP | 101.7°C/W (0 m/s) |

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, $V_{CC} = 2.375V$ TO 3.8V; $V_{EE} = 0V$

| Symbol | Parameter | Test Conditions | | | Minimum | Typical | Maximum | Units |
|----------|-------------------------|-----------------|--|--|---------|---------|---------|-------|
| V_{CC} | Positive Supply Voltage | | | | 2.375 | 3.3 | 3.8 | V |
| I_{EE} | Power Supply Current | | | | | 18 | | mA |

TABLE 3B. LVPECL DC CHARACTERISTICS, $V_{CC} = 3.3V$; $V_{EE} = 0V$

| Symbol | Parameter | -40°C | | | 25°C | | | 85°C | | | Units |
|-----------|--|-------------|-------|-----|------|-------|-----|------|-------|-----|-------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| V_{OH} | Output High Voltage; NOTE 1 | | 2.275 | | | 2.295 | | | 2.295 | | V |
| V_{OL} | Output Low Voltage; NOTE 1 | | 1.545 | | | 1.52 | | | 1.535 | | V |
| V_{PP} | Peak-to-Peak Input Voltage | | 800 | | | 800 | | | 800 | | V |
| V_{CMR} | Input High Voltage Common Mode Range; NOTE 2, 3 | | | | | | | | | | V |
| I_{IH} | Input High Current | PCLK, nPCLK | | | | | | | | | µA |
| I_{IL} | Input Low Current | PCLK | | | | | | | | | µA |
| | | nPCLK | | | | | | | | | µA |

Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.

NOTE 2: Common mode voltage is defined as V_{IH} .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$.

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

TABLE 3C. LVPECL DC CHARACTERISTICS, $V_{CC} = 2.5V$; $V_{EE} = 0V$

| Symbol | Parameter | -40°C | | | 25°C | | | 85°C | | | Units |
|-----------|--|-------------|-------|-----|------|-------|-----|------|-------|-----|---------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| V_{OH} | Output High Voltage; NOTE 1 | | 1.475 | | | 1.495 | | | 1.495 | | V |
| V_{OL} | Output Low Voltage; NOTE 1 | | 0.745 | | | 0.72 | | | 0.735 | | V |
| V_{PP} | Peak-to-Peak Input Voltage | | 800 | | | 800 | | | 800 | | V |
| V_{CMR} | Input High Voltage Common Mode Range; NOTE 2, 3 | | | | | | | | | | V |
| I_{IH} | Input High Current | PCLK, nPCLK | | | | | | | | | μA |
| I_{IL} | Input Low Current | PCLK | | | | | | | | | μA |
| | | nPCLK | | | | | | | | | μA |

Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.

NOTE 2: Common mode voltage is defined as V_{IH} .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$.

TABLE 3D. ECL DC CHARACTERISTICS, $V_{CC} = 0V$; $V_{EE} = -3.8V$ TO $-2.375V$

| Symbol | Parameter | -40°C | | | 25°C | | | 85°C | | | Units |
|-----------|--|-------------|--------|-----|------|--------|-----|------|--------|-----|---------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| V_{OH} | Output High Voltage; NOTE 1 | | -1.025 | | | -1.005 | | | -1.005 | | V |
| V_{OL} | Output Low Voltage; NOTE 1 | | -1.755 | | | -1.78 | | | -1.765 | | V |
| V_{PP} | Peak-to-Peak Input Voltage | | 800 | | | 800 | | | 800 | | V |
| V_{CMR} | Input High Voltage Common Mode Range; NOTE 2, 3 | | | | | | | | | | V |
| I_{IH} | Input High Current | PCLK, nPCLK | | | | | | | | | μA |
| I_{IL} | Input Low Current | PCLK | | | | | | | | | μA |
| | Low Current | nPCLK | | | | | | | | | μA |

Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to $V_{CCO} - 2V$.

NOTE 2: Common mode voltage is defined as V_{IH} .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is $V_{CC} + 0.3V$.

TABLE 4. AC CHARACTERISTICS, $V_{CC} = 0V$; $V_{EE} = -3.8V$ TO $-2.375V$ OR $V_{CC} = 2.375$ TO $3.8V$; $V_{EE} = 0V$

| Symbol | Parameter | -40°C | | | 25°C | | | 85°C | | | Units |
|-----------|------------------------------|---------------|-----|-----|------|-----|-----|------|-----|-----|-------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f_{MAX} | Output Frequency | | 3 | | | 3 | | | 3 | | GHz |
| t_{PD} | Propagation Delay; NOTE 1 | | 240 | | | 250 | | | 260 | | ps |
| $tsk(o)$ | Output Skew; NOTE 2, 4 | | 5 | | | 5 | | | 5 | | ps |
| $tsk(pp)$ | Part-to-Part Skew; NOTE 3, 4 | | | | | | | | | | ps |
| t_R/t_F | Output Rise/Fall Time | 20% to 80% | 160 | | | 160 | | | 160 | | ps |
| odc | Output Duty Cycle | $f \leq 1GHz$ | 50 | | | 50 | | | 50 | | % |

All parameters are measured at $f \leq 1.7GHz$, unless otherwise noted.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

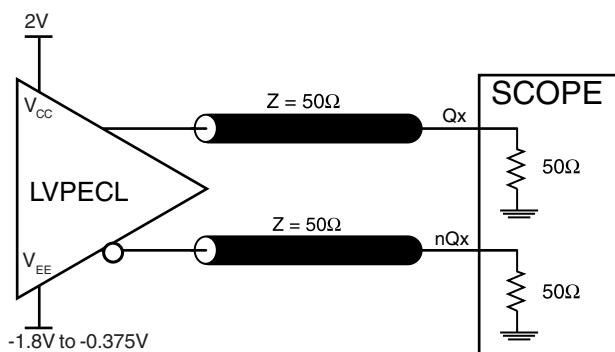
Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

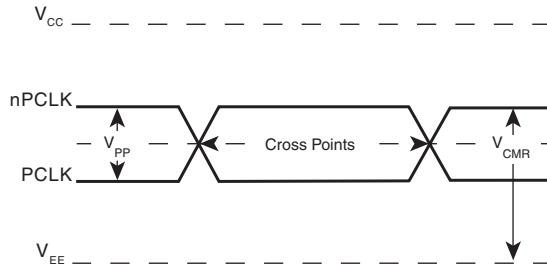
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



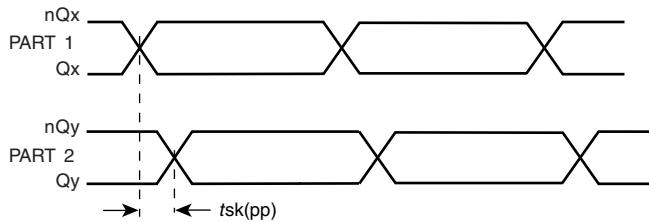
PARAMETER MEASUREMENT INFORMATION



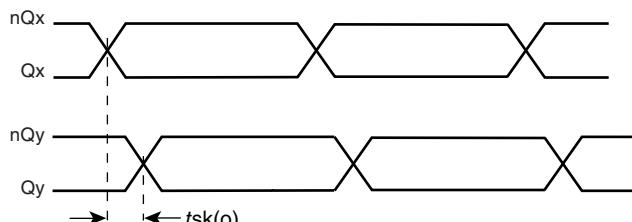
OUTPUT LOAD AC TEST CIRCUIT



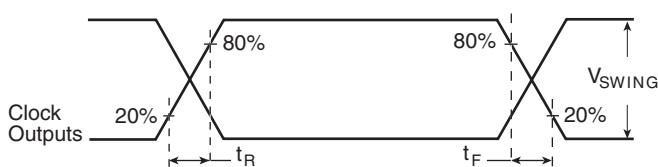
DIFFERENTIAL INPUT LEVEL



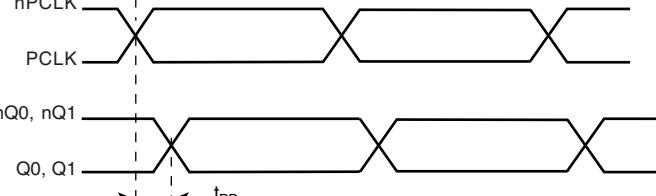
PART-TO-PART SKEW



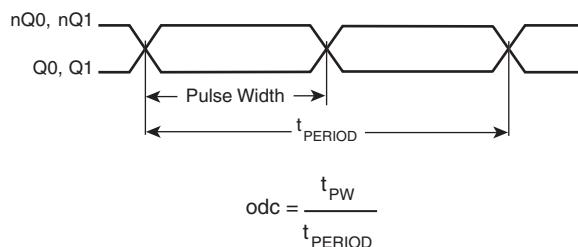
OUTPUT SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



Integrated
Circuit
Systems, Inc.

PRELIMINARY

ICS853011C

Low Skew, 1-to-2

Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer

APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{CC}/2$ is generated by the bias resistors $R1$, $R2$ and $C1$. This bias circuit should be located as close as possible to the input pin. The ratio

of $R1$ and $R2$ might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{CC} = 3.3V$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.

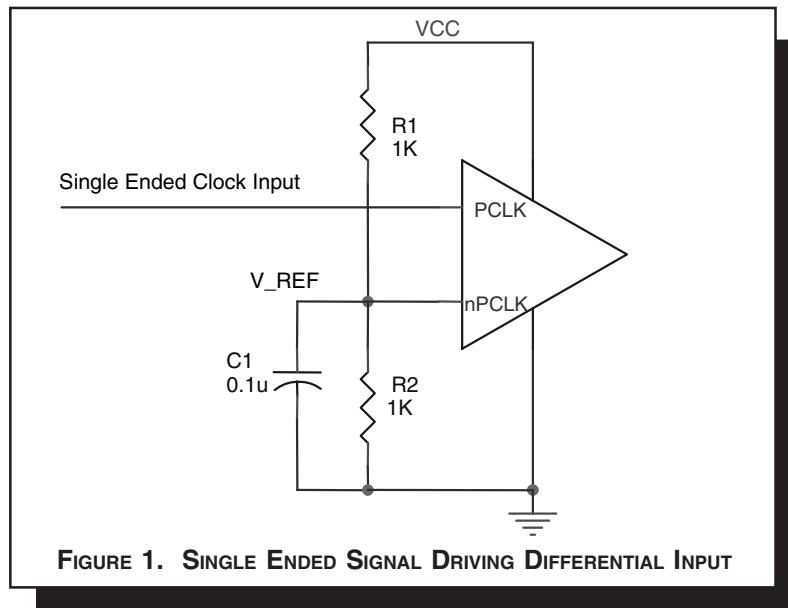


FIGURE 1. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

TERMINATION FOR 3.3V LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

$FOUT$ and $nFOUT$ are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figures 2A and 2B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

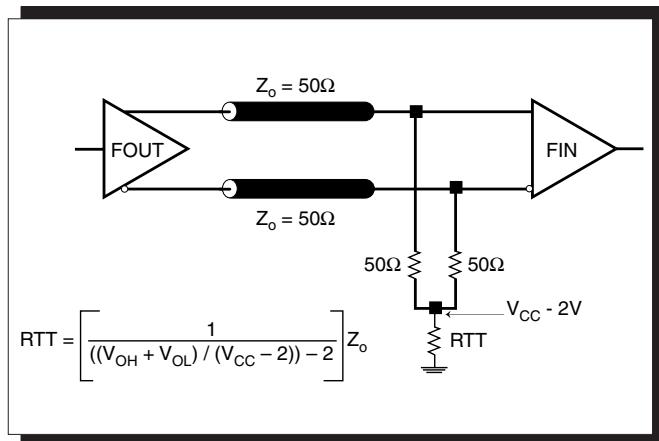


FIGURE 2A. LVPECL OUTPUT TERMINATION

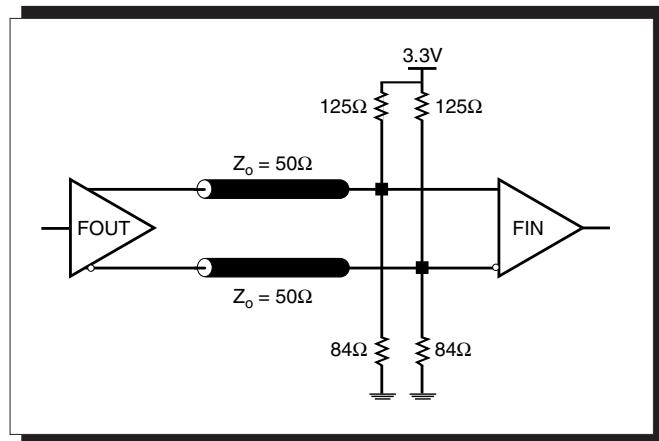


FIGURE 2B. LVPECL OUTPUT TERMINATION

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

TERMINATION FOR 2.5V LVPECL OUTPUT

Figure 3A and Figure 3B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating 50Ω to $V_{cc} - 2V$. For $V_{cc} = 2.5V$, the $V_{cc} - 2V$ is very close to

ground level. The $R3$ in Figure 3B can be eliminated and the termination is shown in Figure 3C.

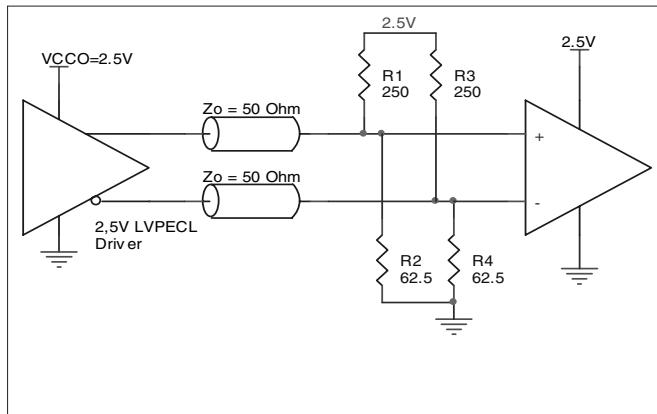


FIGURE 3A. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

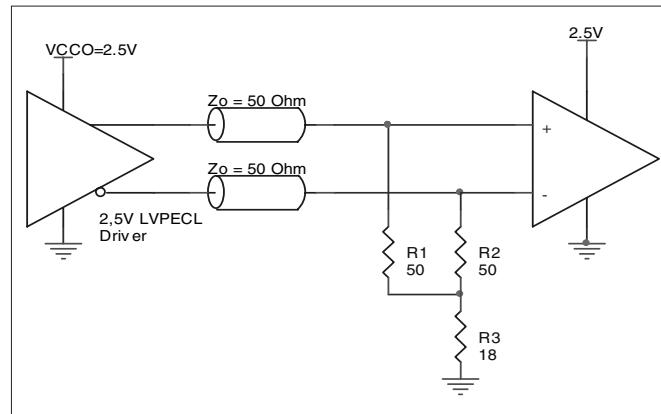


FIGURE 3B. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

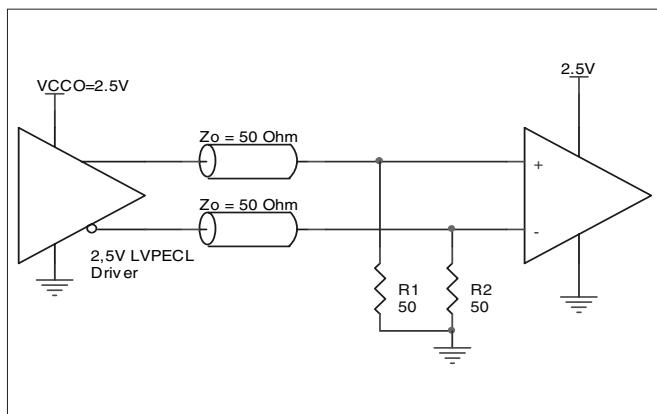


FIGURE 3C. 2.5V LVPECL TERMINATION EXAMPLE



Integrated
Circuit
Systems, Inc.

PRELIMINARY

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both V_{SWING} and V_{OH} must meet the V_{PP} and V_{CMR} input requirements. Figures 4A to 4E show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

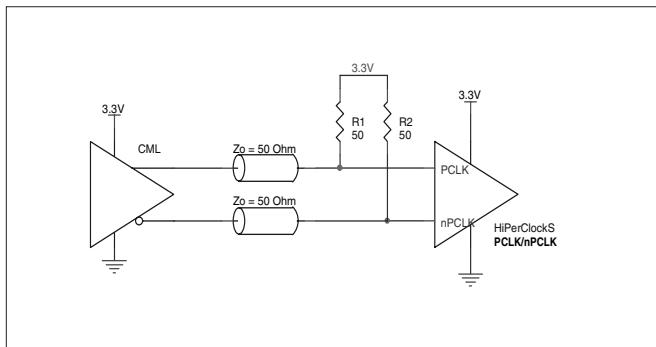


FIGURE 4A. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A CML DRIVER

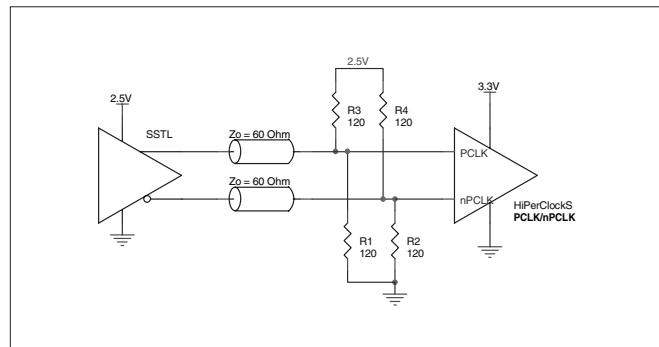


FIGURE 4B. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

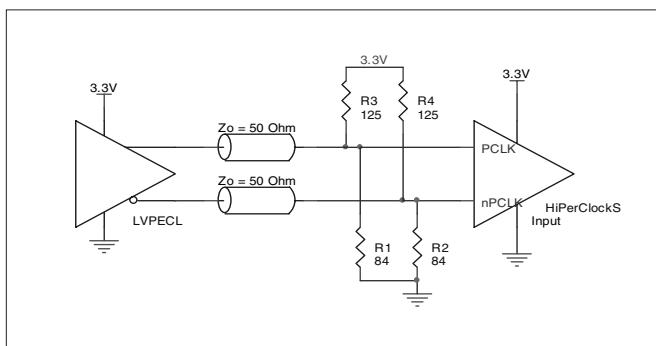


FIGURE 4C. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER

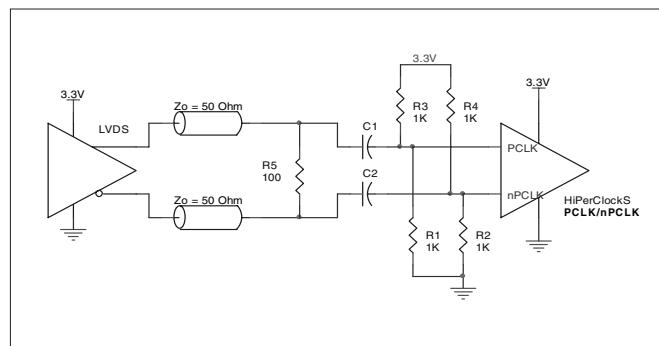


FIGURE 4D. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER

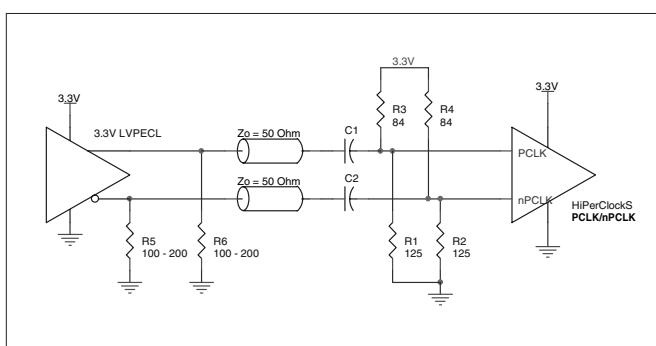


FIGURE 4E. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS853011C. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS853011C is the sum of the core power plus the power dissipated in the load(s).

The following is the power dissipation for $V_{CC} = 3.8V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.8V * 18mA = 68.4mW$
- Power (outputs)_{MAX} = **30.94mW/Loaded Output pair**
If all outputs are loaded, the total power is $2 * 30.94mW = 61.88mW$

Total Power_{MAX} (3.8V, with all outputs switching) = $68.4mW + 61.88mW = 130.3mW$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 103.3°C/W per Table 5A below.

Therefore, T_j for an ambient temperature of 85°C with all outputs switching is:

$85^\circ C + 0.130W * 103.3^\circ C/W = 98.4^\circ C$. This is well below the limit of 125°C.

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 5A. THERMAL RESISTANCE θ_{JA} FOR 8-PIN SOIC, FORCED CONVECTION

| θ_{JA} by Velocity (Linear Feet per Minute) | | | |
|---|-----------|------------|------------|
| | 0 | 200 | 500 |
| Single-Layer PCB, JEDEC Standard Test Boards | 153.3°C/W | 128.5°C/W | 115.5°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards | 112.7°C/W | 103.3°C/W | 97.1°C/W |
| NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs. | | | |

TABLE 5B. THERMAL RESISTANCE θ_{JA} FOR 8-PIN TSSOP, FORCED CONVECTION

| θ_{JA} by Velocity (Meters per Second) | | | |
|---|-----------|----------|----------|
| | 0 | 1 | 2 |
| Multi-Layer PCB, JEDEC Standard Test Boards | 101.7°C/W | 90.5°C/W | 89.8°C/W |

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

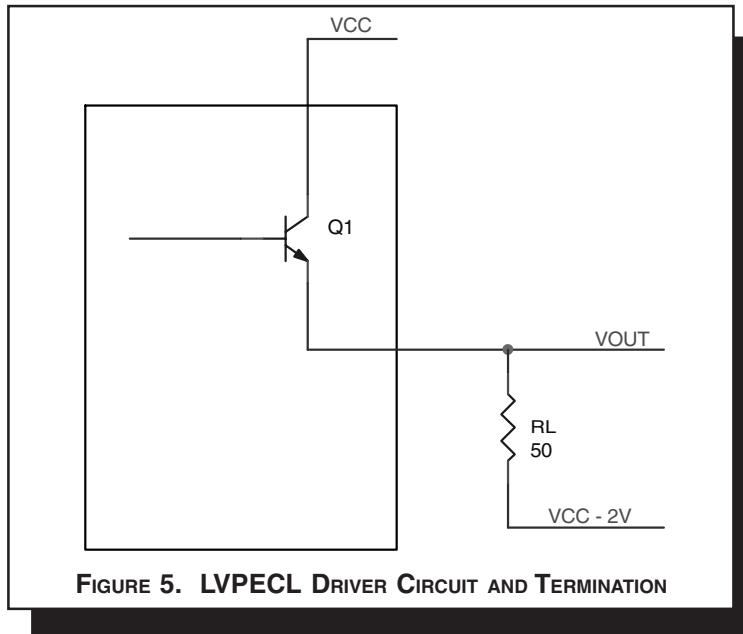
Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 5*.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CC} - 2V$.

- For logic high, $V_{OUT} = V_{OH_{MAX}} = V_{CC_{MAX}} - 0.935V$

$$(V_{CC_{MAX}} - V_{OH_{MAX}}) = 0.935V$$

- For logic low, $V_{OUT} = V_{OL_{MAX}} = V_{CC_{MAX}} - 1.67V$

$$(V_{CC_{MAX}} - V_{OL_{MAX}}) = 1.67V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_{MAX}} - (V_{CC_{MAX}} - 2V))/R_L] * (V_{CC_{MAX}} - V_{OH_{MAX}}) = [(2V - (V_{CC_{MAX}} - V_{OH_{MAX}}))/R_L] * (V_{CC_{MAX}} - V_{OH_{MAX}}) = [(2V - 0.935V)/50\Omega] * 0.935V = 19.92mW$$

$$Pd_L = [(V_{OL_{MAX}} - (V_{CC_{MAX}} - 2V))/R_L] * (V_{CC_{MAX}} - V_{OL_{MAX}}) = [(2V - (V_{CC_{MAX}} - V_{OL_{MAX}}))/R_L] * (V_{CC_{MAX}} - V_{OL_{MAX}}) = [(2V - 1.67V)/50\Omega] * 1.67V = 11.02mW$$

Total Power Dissipation per output pair = $Pd_H + Pd_L = 30.94mW$

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

RELIABILITY INFORMATION

TABLE 6A. θ_{JA} vs. AIR FLOW TABLE FOR 8 LEAD SOIC

θ_{JA} by Velocity (Linear Feet per Minute)

| | 0 | 200 | 500 |
|--|-----------|-----------|-----------|
| Single-Layer PCB, JEDEC Standard Test Boards | 153.3°C/W | 128.5°C/W | 115.5°C/W |
| Multi-Layer PCB, JEDEC Standard Test Boards | 112.7°C/W | 103.3°C/W | 97.1°C/W |

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TABLE 6B. θ_{JA} vs. AIR FLOW TABLE FOR 8 LEAD TSSOP

θ_{JA} by Velocity (Meters per Second)

| | 0 | 1 | 2 |
|---|-----------|----------|----------|
| Multi-Layer PCB, JEDEC Standard Test Boards | 101.7°C/W | 90.5°C/W | 89.8°C/W |

TRANSISTOR COUNT

The transistor count for ICS853011C is: 96

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C
Low Skew, 1-to-2
Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer

PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

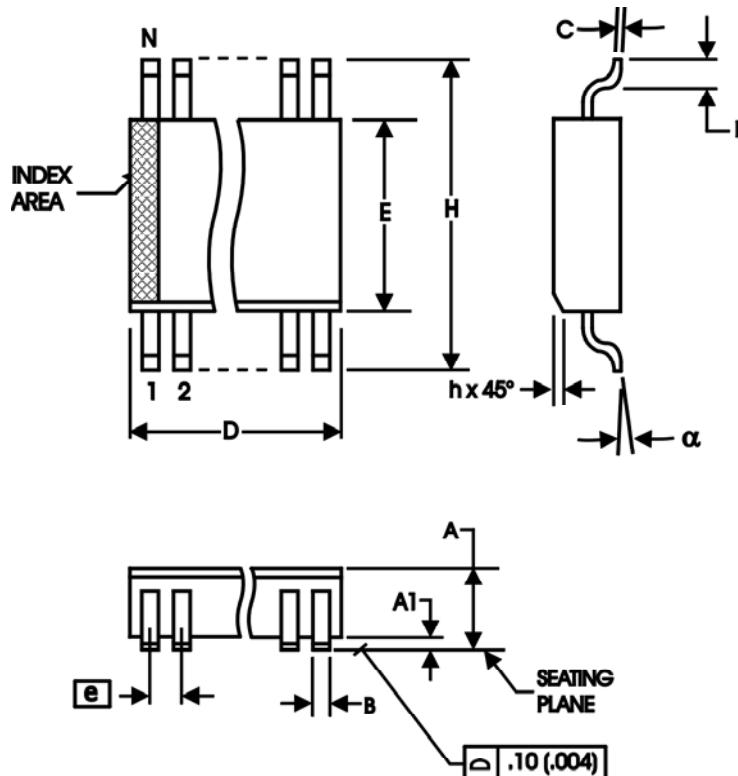


TABLE 7A. PACKAGE DIMENSIONS

| SYMBOL | Millimeters | |
|--------|-------------|---------|
| | MINIMUM | MAXIMUM |
| N | 8 | |
| A | 1.35 | 1.75 |
| A1 | 0.10 | 0.25 |
| B | 0.33 | 0.51 |
| C | 0.19 | 0.25 |
| D | 4.80 | 5.00 |
| E | 3.80 | 4.00 |
| e | 1.27 BASIC | |
| H | 5.80 | 6.20 |
| h | 0.25 | 0.50 |
| L | 0.40 | 1.27 |
| α | 0° | 8° |

Reference Document: JEDEC Publication 95, MS-012

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

PACKAGE OUTLINE - G SUFFIX FOR 8 LEAD TSSOP

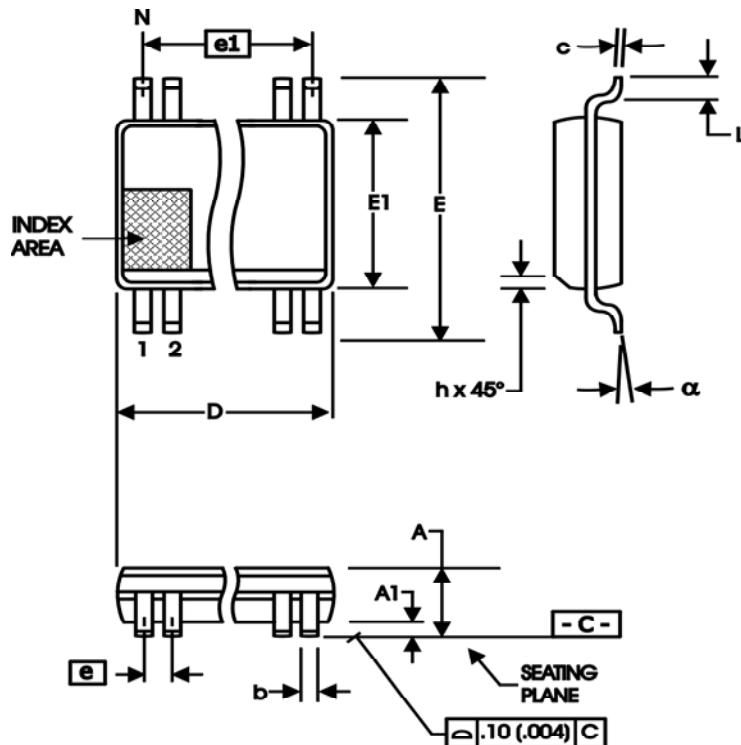


TABLE 7B. PACKAGE DIMENSIONS

| SYMBOL | Millimeters | |
|--------|-------------|---------|
| | Minimum | Maximum |
| N | 8 | |
| A | -- | 1.10 |
| A1 | 0 | 0.15 |
| A2 | 0.79 | 0.97 |
| b | 0.22 | 0.38 |
| c | 0.08 | 0.23 |
| D | 3.00 BASIC | |
| E | 4.90 BASIC | |
| E1 | 3.00 BASIC | |
| e | 0.65 BASIC | |
| e1 | 1.95 BASIC | |
| L | 0.40 | 0.80 |
| α | 0° | 8° |
| aaa | -- | 0.10 |

Reference Document: JEDEC Publication 95, MO-187

PRELIMINARY



Integrated
Circuit
Systems, Inc.

ICS853011C

Low Skew, 1-to-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

TABLE 8. ORDERING INFORMATION

| Part/Order Number | Marking | Package | Count | Temperature |
|-------------------|---------|--|-------------|---------------|
| ICS853011CM | 853011C | 8 lead SOIC | 96 per tube | -40°C to 85°C |
| ICS853011CMT | 853011C | 8 lead SOIC on Tape and Reel | 2500 | -40°C to 85°C |
| ICS853011CMLF | 3011CLF | "Lead Free" 8 lead SOIC | 96 per tube | -40°C to 85°C |
| ICS853011CMLFT | 3011CLF | "Lead Free" 8 lead SOIC on Tape and Reel | 2500 | -40°C to 85°C |
| ICS853011CG | 011C | 8 lead TSSOP | 96 per tube | -40°C to 85°C |
| ICS853011CGT | 011C | 8 lead TSSOP on Tape and Reel | 2500 | -40°C to 85°C |

The aforementioned trademark, HiPerClock™ is a trademark of Integrated Circuit Systems, Inc. or its subsidiaries in the United States and/or other countries.

While the information presented herein has been checked for both accuracy and reliability, Integrated Circuit Systems, Incorporated (ICS) assumes no responsibility for either its use or for infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial and industrial applications. Any other applications such as those requiring high reliability or other extraordinary environmental requirements are not recommended without additional processing by ICS. ICS reserves the right to change any circuitry or specifications without notice. ICS does not authorize or warrant any ICS product for use in life support devices or critical medical instruments.